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**Part Number:** **0736441216**  
**Status:** **Active**  
**Overview:** HDM® Backplane Connector System  
**Description:** HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location B, Polarizing Key Position N/A, 144 Circuits

**Documents:**

[3D Model](#) [Test Summary TS-73670-990 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**Agency Certification**

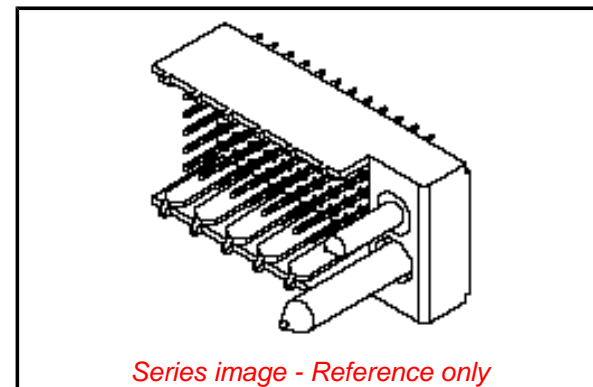
CSA LR19980  
 UL E29179

**General**

Product Family Backplane Connectors  
 Series 73644  
 Application Backplane  
 Comments Standard Press-Fit  
 Component Type PCB Header  
 Overview HDM® Backplane Connector System  
 Product Name HDM®  
 UPC 800755023442

**Physical**

Circuits (Loaded) 144  
 Circuits (maximum) 144  
 Color - Resin Black, Natural  
 Durability (mating cycles max) 250  
 First Mate / Last Break No  
 Flammability 94V-0  
 Guide to Mating Part Yes  
 Keying to Mating Part None  
 Material - Metal Phosphor Bronze, Stainless Steel  
 Material - Plating Mating Gold  
 Material - Plating Termination Gold  
 Material - Resin High Temperature Thermoplastic  
 Net Weight 9.026/g  
 Number of Columns 24  
 Number of Pairs Open Pin Field  
 Number of Rows 6  
 Orientation Vertical  
 PC Tail Length 3.50mm  
 PCB Locator No  
 PCB Retention Yes  
 PCB Thickness - Recommended 2.50mm  
 Packaging Type Tube  
 Pitch - Mating Interface 2.00mm  
 Pitch - Termination Interface 2.00mm  
 Plating min - Mating 0.762µm  
 Plating min - Termination 0.051µm  
 Polarized to PCB No  
 Stackable Yes  
 Surface Mount Compatible (SMC) Yes  
 Temperature Range - Operating -55°C to +105°C  
 Termination Interface: Style Through Hole - Compliant Pin



Series image - Reference only

**EU ELV**

**Not Relevant**

**EU RoHS**

**Compliant**

**REACH SVHC**

Contains SVHC(2014 December 17): No

**Halogen-Free**

**Status**

**Low-Halogen**

**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS

ELV

Green Image

Not Relevant

**Search Parts in this Series**

73644 Series

**Mates With**

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle, 73780 HDM® Board-to-Board Daughtercard Receptacle

**Application Tooling | FAQ**

*Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.*

**Global**

| Description           | Product #         |
|-----------------------|-------------------|
| Extraction Tool       | <u>0621001000</u> |
| Backplane Insertion   | <u>0621001400</u> |
| Signal Contact Tool   |                   |
| Backplane Insertion   | <u>0622005703</u> |
| Head for 144 Circuits |                   |

**Electrical**

|                               |          |
|-------------------------------|----------|
| Current - Maximum per Contact | 1.0A     |
| Data Rate                     | 1.0 Gbps |
| Real Signals (per 25mm)       | 75       |
| Shielded                      | No       |
| Voltage - Maximum             | 250V AC  |

**Solder Process Data**

|                              |     |
|------------------------------|-----|
| Lead-free Process Capability | N/A |
|------------------------------|-----|

**Material Info****Reference - Drawing Numbers**

|               |                |
|---------------|----------------|
| Sales Drawing | SDA-73644-**** |
| Test Summary  | TS-73670-990   |

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